

WHAT IS CLAIMED IS:

1. A dicing apparatus dividing a wafer having a plurality of devices formed thereon into individual device chips, the wafer being supported by an annular frame through an adhesive tape, comprising:

a chuck table including a wafer support table that supports the wafer thereon, and a plurality of frame support portions which are disposed on an outer periphery of the wafer support table and support the annular frame;-
and

cutting means performing cutting processing on the wafer supported on the wafer support table;

cleaning means ejecting a cleaning water onto the wafer, the adhesive tape, and the annular frame supported on the chuck table for cleaning when moving means, which moves the chuck table between a processing region where the cutting processing is performed on the wafer and an attaching/detaching region where the wafer is placed and held on the chuck table and where the wafer for which cutting processing has been performed is unloaded from the chuck table, moves the wafer for which cutting processing has been performed from the processing region to the attaching/detaching region; and

air blowing means ejecting high pressure air,

blowing off the cleaning water left on the wafer, the adhesive tape, and the annular frame, and obtaining a dry state with moisture removed;

wherein

the wafer support table ~~including~~includes a support substrate having a front surface portion supporting the wafer thereon and through which ultraviolet rays pass and ultraviolet irradiation means irradiating ultraviolet rays such that an adhesive force of the adhesive tape in a region corresponding to the wafer is reduced~~;~~;

~~2. The dicing apparatus according to claim 1,~~

~~wherein the wafer support table includes a support substrate which has a front surface portion supporting the wafer thereon and through which ultraviolet rays pass, and~~

the ultraviolet irradiation means includes an ultraviolet irradiation source disposed on a back surface side of the support substrate~~,~~, and irradiates the ultraviolet rays in a state in which the cleaning water remains on the wafer and the adhesive tape; and

~~3. The dicing apparatus according to claim 1, further comprising:~~

~~cleaning~~the air blowing means ~~ejecting a~~blows off ~~the~~the cleaning water ~~on~~toleft on the wafer, the adhesive

tape, and the annular frame ~~supported on the chuck table~~
~~for cleaning,~~ and obtains the dry state with moisture
removed after the ultraviolet irradiation means irradiate
the ultraviolet rays.